
This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A resin composition used for fabricating an interlayer dielectric of a printed wiring board, wherein said composition comprises; a) an epoxy based resin; b) an epoxy resin curing agent containing 5 to 25% by weight nitrogen; c) maleimide compounds having thermosetting properties; d) polymers having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary, wherein said resin composition is free of halogen.
2. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said epoxy based resin comprises epoxy resins having two or more glycidyl groups per molecule, and said epoxy resin curing agent comprises a phenol novolak epoxy resin curing agent containing triazine rings within a molecule.
3. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said epoxy based resin is selected from the group consisting of bisphenol A epoxy resin, bisphenol F epoxy resin, novolak epoxy resin, cresol novolak epoxy resin, glycidylamine epoxy resin, and combinations thereof.
4. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said polymers having crosslinkable

functional groups are selected from the group consisting of polyether sulfone resin having a terminal hydroxyl group, polyvinyl acetal resin having repeated hydroxyl groups, phenoxy resin, and combinations thereof.

5. (Currently Amended) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said epoxy resin curing agent is ~~selected from the group consisting of melamine, benzoguanamine, a phenol novolak epoxy-~~
curing agent comprising (a) one or two of melamine and benzoguanamine, and (b) a compound
obtained from a condensation reaction of phenols and formaldehydes wherein the phenol
novolak epoxy-resin curing agent has a nitrogen content of 5 to 25 wt%.

6. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 1, wherein said maleimide compounds are selected from the group consisting of N,N'-(4,4-diphenylmethane)bismaleimide; bis(3-ethyl-5-methyl-4-maleimidephenyl)methane; 2,2-bis[4-(4-maleimidephenoxy)phenyl]propane; thermosetting maleimide compounds obtained from Michael addition reaction of these maleimide compounds and polyamines; and combinations thereof.

7. (Currently Amended) A method for producing a resin composition used for fabricating an interlayer dielectric of the printed wiring board, wherein said resin composition is added to and dissolved in the solvent to a solids content of 40 to 50 % by weight, wherein 100 parts of said

resin composition comprises: 20 to 70 parts by weight of an epoxy based resin; 10 to 50 parts by weight of maleimide compounds having thermosetting properties; 5 to 30 parts by weight of polymers having crosslinkable functional groups within a molecule; and balance being a crosslinker added as necessary and a phenol novolak epoxy resin curing agent containing triazine rings within a molecule, wherein the phenol novolak epoxy-resin curing agent has a nitrogen content of 5 to 25 wt%.

8. (Previously Presented) A method for producing the resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 7, wherein the solvent is a mixed solvent of N-methylpyrrolidone and methyl ethyl ketone, the mixing weight ratio of N-methylpyrrolidone/methyl ethyl ketone being in a range of 50/50 to 40/60.

9. (Previously Presented) A resin sheet for forming an insulating layer used for manufacturing a copper-clad laminate, wherein the resin compound for fabricating the interlayer dielectric of the printed wiring board as set forth in claim 1 is made into a sheet which is in a semi-cured state.

10. (Previously Presented) A resin applied-copper foil constituted by forming a resin layer on a surface of copper foil employing the resin compound for fabricating the interlayer dielectric of the printed wiring board as set forth in any of claims 1.

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11. (Original) The copper-clad laminate manufactured by the use of resin sheet for forming the insulating layer as set forth in claim 9.
12. (Original) The copper-clad laminate manufactured by the use of the resin applied-copper foil as set forth in claim 10.
13. (Currently Amended) A resin composition used for fabricating an interlayer dielectric of a printed wiring board, wherein said composition, comprises; a) an epoxy based resin comprising epoxy resins having two or more glycidyl groups per molecule; b) a phenol novolak epoxy resin curing agent containing triazine rings within a molecule; c) maleimide compounds having thermosetting properties; d) polymers having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary; wherein the phenol novolak epoxy resin curing agent has a nitrogen content of 5 to 25 wt% and said resin composition is free of halogen.
14. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said epoxy based resin is selected from the group consisting of bisphenol A epoxy resin, bisphenol F epoxy resin, novolak epoxy resin, cresol novolak epoxy resin, glycidylamine epoxy resin, and combinations thereof.
15. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said polymers having crosslinkable

functional groups are selected from the group consisting of polyether sulfone resin having a terminal hydroxyl group, polyvinyl acetal resin having repeated hydroxyl groups, phenoxy resin, and combinations thereof.

16. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said epoxy resin curing agent is selected from the group consisting of melamine, benzoguanamine, a compound obtained from a condensation reaction of phenols and formaldehydes; and combinations thereof.

17. (Previously Presented) The resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said maleimide groups are selected from the group consisting of N,N'-(4,4-diphenylmethane)bismaleimide; bis(3-ethyl-5-methyl-4-maleimidephenyl)methane; 2,2-bis[4-(4-maleimidephenoxy)phenyl]propane; thermosetting maleimide compounds obtained from Michael addition reaction of these maleimide compounds and polyamines; and combinations thereof.

18. (Currently Amended) A method for producing a resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 13, wherein said resin composition is added to and dissolved in the solvent to a solids content of 40 to 50 % by weight, wherein 100 parts of said resin composition comprises: 20 to 70 parts by weight of an epoxy based resin; 10 to 50 parts by weight of maleimide compounds having thermosetting properties;

5 to 30 parts by weight of polymers having crosslinkable functional groups within a molecule; and a balance being a crosslinker added as necessary and an a phenol novolak epoxy resin curing agent containing 5 to 25% by weight nitrogen triazine rings within a molecule.

19. (Previously Presented) A method for producing the resin composition used for fabricating an interlayer dielectric of the printed wiring board according to claim 18, wherein the solvent is a mixed solvent of N-methylpyrrolidone and methyl ethyl ketone, the mixing weight ratio of N-methylpyrrolidone/methyl ethyl ketone being in a range of 50/50 to 40/60.

20. (Previously Presented) A printed wiring board comprising a plurality of layers including an interlayer dielectric, the interlayer dielectric comprising a resin composition, wherein said composition comprises; a) an epoxy based resin; b) an epoxy resin curing agent containing 5 to 25% by weight nitrogen; c) maleimide compounds having thermosetting properties; d) polymers having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary, wherein said resin composition is free of halogen.

21. (Currently Amended) A printed wiring board comprising a plurality of layers including an interlayer dielectric, the interlayer dielectric comprising a resin composition, wherein said composition comprises; a) an epoxy based resin comprising epoxy resins having two or more glycidyl groups per molecule; b) a phenol novolak epoxy resin curing agent containing triazine rings within a molecule; c) maleimide compounds having thermosetting properties; d) polymers

having crosslinkable functional groups within a molecule; and e) a crosslinker, which is added if necessary; wherein said resin composition is free of halogen, wherein the phenol novolak epoxy resin curing agent has a nitrogen content of 5 to 25 wt%.